

Application No.: 09/719893

Case No.: 55259US005

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently amended) A heat conductive sheet including a substrate having a thickness from 1 to 7 [[10]] μm and a self-supporting adhesive heat conductive resin layer applied to one surface of said substrate, ~~characterized in that said~~ wherein the heat conductive resin layer contains a binder resin, and a heat conductive filler dispersed in said binder resin.
2. (Original) A heat conductive sheet according to claim 1, wherein said substrate comprises a plastic film, a metal foil or a single spread adhesive film.
3. (Previously presented) A heat conductive sheet according to claim 1, wherein said substrate comprises a polyolefin film or a polyester film.
4. (Original) A heat conductive sheet according to claim 1, wherein said heat conductive resin layer is formed by applying a film-forming resin composition to the surface of said substrate under the state where said substrate is held on a support.
5. (Previously presented) A heat conductive sheet according to claim 1, wherein said binder resin comprises at least one resin selected from a silicone gel resin, a urethane resin, a synthetic rubber resin, and an acrylic thermoplastic resin.
6. (Original) A heat conductive sheet according to claim 1, wherein said binder resin comprises at least one of a silicone gel resin and a urethane resin.
7. (Original) A heat conductive sheet according to claim 1, wherein said heat conductive filler comprises an inorganic filler.

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8. (Currently amended) A heat conductive sheet according to claim 1, wherein said heat conductive filler comprises two or more inorganic filler particles having mutually different ~~article~~ particle diameters.
9. (Original) A heat conductive sheet according to claim 1, wherein said heat conductive filler comprises silicon carbide particles and boron nitride particles.
10. (Canceled)
11. (Previously presented) A heat conductive sheet according to claim 1, wherein said heat conductive resin layer is applied to only one surface of said substrate.
12. (Currently amended) The method of claim 21 ~~[[10]]~~ wherein the heat conductive resin layer is applied to only one surface of said substrate.
13. (Currently amended) The method of claim 21 ~~[[10]]~~ further comprising applying a release liner to the film-forming resin composition to form a laminate.
14. (Previously presented) The method of claim 13 further comprising applying heat and pressure to the laminate before the step of separating the support.
15. (Currently amended) The method of claim 21 ~~[[10]]~~ wherein the heat conductive resin layer is cured.
16. (Currently amended) The method of claim 21 ~~[[10]]~~ further comprising providing an adhesive film on the support beneath the substrate.
17. (Previously presented) The method of claim 13 further comprising providing an adhesive film on the support beneath the substrate.

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18. (Previously presented) A heat conductive sheet according to claim 1, wherein said substrate comprises a plastic film having a thickness from 1 to 7 μm ., a metal foil or a single spread adhesive film.

19. (Previously presented) A heat conductive sheet according to claim 1, wherein said substrate comprises a metal foil having a thickness from 1 to 7 μm .

20. (Previously presented) A heat conductive sheet according to claim 1, wherein said substrate comprises a single spread adhesive film having a thickness from 1 to 7 μm .

21. (New) A method of producing a heat conductive sheet including a substrate and a heat conductive resin layer applied to a first surface of said substrate, comprising the steps of supporting said substrate by a support by releasably bonding a second surface of the substrate to the support; applying a film-forming resin composition containing a binder resin and a heat conductive filler to the first surface of said substrate to form a self-supporting adhesive heat conductive resin layer; and separating the resulting heat conductive sheet from said support.